

256K x 4 Static RAM

Features

- · High speed
 - $t_{AA} = 15 \text{ ns}$
- CMOS for optimum speed/power
- Low active power
 - 495 mW
- · Low standby power
 - 275 mW
- 2.0V data retention (optional)
- · Automatic power-down when deselected
- TTL-compatible inputs and outputs

Functional Description

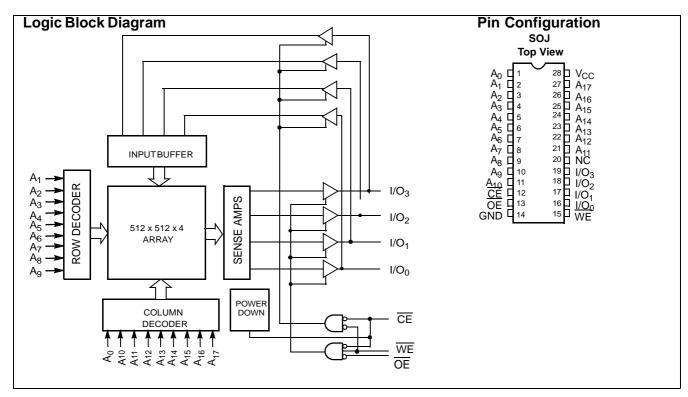
The CY7C106BN and CY7C1006BN are high-performance CMOS static RAMs organized as 262,144 words by 4 bits. Easy memory expansion is provided by an active LOW Chip Enable (CE), an active LOW Output Enable (OE), and three-state drivers. These devices have an automatic power-down feature that reduces power consumption by more than 65% when the devices are deselected.

<u>Writing</u> to the devices is <u>ac</u>complished by taking Chip Enable ($\overline{\text{CE}}$) and Write Enable ($\overline{\text{WE}}$) inputs LOW. Data on the four I/O pins (I/O $_0$ through I/O $_3$) is then written into the location specified on the address pins (A $_0$ through A $_{17}$).

Reading from the devices is accomplished by taking Chip Enable ($\overline{\text{CE}}$) and Output Enable ($\overline{\text{OE}}$) LOW while forcing Write Enable (WE) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the four I/O pins.

The four input/output pins (I/O $_0$ through I/O $_3$) are placed in a high-impedance state when the <u>devi</u>ces are deselected (CE HIGH), the <u>outputs are</u> disabled (OE HIGH), or during a write operation (CE and WE LOW).

The CY7C106BN is available in a standard 400-mil-wide SOJ; the CY7C1006BN is available in a standard 300-mil-wide SOJ.





Selection Guide

	7C106BN-15 7C1006BN-15	7C106BN-20 7C1006BN-20
Maximum Access Time (ns)	15	20
Maximum Operating Current (mA)	80	75
Maximum Standby Current (mA)	30	30

Maximum Ratings (Above which the useful life may be impaired. For user guide lines, not tested.)	}-
Storage Temperature65xC to +150xC	;
Ambient Temperature with Power Applied55xC to +125xC	
Supply Voltage on V _{CC} Relative to GND ^[1] –0.5V to +7.0V	/
DC Voltage Applied to Outputs in High Z State $^{[1]}$	
. 6	

Current into Outputs (LOW)	20 mA
Static Discharge Voltage(per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	.>200 mA

Operating Range

Range	Ambient Temperature ^[2]	V _{CC}
Commercial	0°C to +70°C	5V ± 10%
Industrial	–45°C to +85°C	

Electrical Characteristics Over the Operating Range

					6BN-15 06BN-15	7C106BN-20 7C1006BN-20		
Parameter	Description	Test Conditions	Test Conditions		Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0 \text{ m/s}$	4	2.4		2.4		V
V _{OL}	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0 \text{ mA}$			0.4		0.4	V
V _{IH}	Input HIGH Voltage			2.2	$V_{CC} + 0.3$	2.2	$V_{CC} + 0.3$	V
V _{IL}	Input LOW Voltage ^[1]			-0.3	0.8	-0.3	0.8	V
I _{IX}	Input Leakage Current	$GND \le V_1 \le V_{CC}$	$GND \le V_1 \le V_{CC}$			-1	+1	mΑ
I _{OZ}	Output Leakage Current	$\begin{array}{l} \text{GND} \leq \text{V}_{\text{I}} \leq \text{V}_{\text{CC}}, \text{Output} \\ \text{Disabled} \end{array}$	- 5	+5	– 5	+5	mA	
I _{OS}	Output Short Circuit Current ^[3]	$V_{CC} = Max., V_{OUT} = GND$		-300		-300	mA	
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = Max.$, $I_{OUT} = 0$ mA, $f = f_{MAX} = 1/t_{RC}$		80		75	mA	
I _{SB1}	Automatic CE Power-Down Current —TTL Inputs	$\begin{aligned} &\text{Max. } V_{CC}, \overline{CE} \ge V_{IH}, V_{IN} \ge Y_{IN} \le Y_{IL}, & \text{f} = f_{MAX} \end{aligned}$		30		30	mA	
I _{SB2}	Automatic CE Power-Down Current —CMOS Inputs	$\label{eq:local_control_control} \begin{array}{ll} \underline{\text{Max}}. \ V_{\text{CC}}, \\ \hline \text{CE} \geq V_{\text{CC}} - 0.3 \text{V}, \\ V_{\text{IN}} \geq V_{\text{CC}} - 0.3 \text{V} \\ \text{or} \ V_{\text{IN}} \leq 0.3 \text{V}, \ \text{f=0} \end{array}$	om'l		10		10	mA

Capacitance^[4]

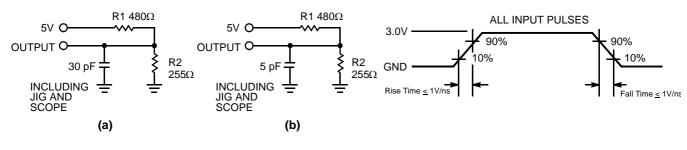
Parameter	Description	Test Conditions	Max.	Unit
C _{IN} : Addresses	Input Capacitance	$T_A = 25 \times C$, $f = 1$ MHz,	7	pF
C _{IN} : Controls		$V_{CC} = 5.0V$	10	pF
C _{OUT}	Output Capacitance		10	pF

Notes:

- V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
 T_A is the "instant on" case temperature.
 Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
 Tested initially and after any design or process changes that may affect these parameters.



AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT

Switching Characteristics Over the Operating Range^[5]

		7C10 7C10	6B-15 06B-15		06B-20 06B-20	
Parameter	Description	Min.	Max.	Min.	Max.	Unit
READ CYCLE			-	•	<u>'</u>	
t _{RC}	Read Cycle Time	15		20		ns
t _{AA}	Address to Data Valid		15		20	ns
t _{OHA}	Data Hold from Address Change	3		3		ns
t _{ACE}	CE LOW to Data Valid		15		20	ns
t _{DOE}	OE LOW to Data Valid		7		8	ns
t _{LZOE}	OE LOW to Low Z	0		0		ns
t _{HZOE}	OE HIGH to High Z ^[6, 7]		7		8	ns
t _{LZCE}	CE LOW to Low Z ^[7]	3		3		ns
t _{HZCE}	CE HIGH to High Z ^[6, 7]		7		8	ns
t _{PU}	CE LOW to Power-Up	0		0		ns
t _{PD}	CE HIGH to Power-Down		15		20	ns
WRITE CYCLE	[8, 9]	•		•	<u>'</u>	
t _{WC}	Write Cycle Time	15		20		ns
t _{SCE}	CE LOW to Write End	12		15		ns
t _{AW}	Address Set-Up to Write End	12		15		ns
t _{HA}	Address Hold from Write End	0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		ns
t _{PWE}	WE Pulse Width	12		15		ns
t _{SD}	Data Set-Up to Write End	8		10		ns
t _{HD}	Data Hold from Write End	0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[7]	3		3		ns
t _{HZWE}	WE LOW to High Z ^[6, 7]		7		8	ns

^{5.} Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified l_{OL}/l_{OH} and 30-pF load capacitance.

6. l_{HZOE} , l_{HZOE} , and l_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.

7. At any given temperature and voltage condition, l_{HZCE} is less than l_{LZOE} , l_{HZOE} is less than l_{LZOE} , and l_{HZWE} is less than l_{LZWE} for any given device.

8. The internal write time of the memory is defined by the overlap of CE and WE LOW. CE and WE must be LOW to initiate a write, and the transition of either of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.

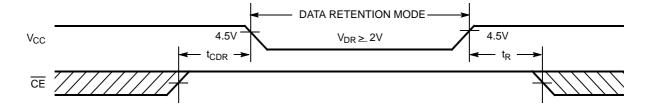
9. The minimum write cycle time for Write Cycle No. 3 (WE controlled, OE LOW) is the sum of l_{HZWE} and l_{SD} .



Data Retention Characteristics Over the Operating Range

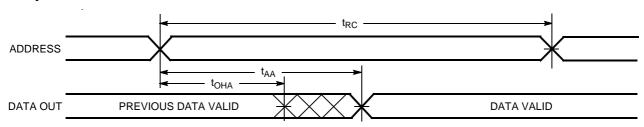
Parameter	Description	Conditions ^[10]	Min.	Max.	Unit
V_{DR}	V _{CC} for Data Retention		2.0		V
I _{CCDR}	Data Retention Current	$\frac{V_{CC}}{V_{CC}} = V_{DR} = 2.0V,$		250	μΑ
t _{CDR} ^[4]	Chip Deselect to Data Retention Time	$\overrightarrow{CE} \ge V_{CC} - 0.3V$, $V_{IN} \ge V_{CC} - 0.3V$ or	0		ns
t _R ^[4]	Operation Recovery Time	V _{IN} ≤ 0.3V	200		ms

Data Retention Waveform

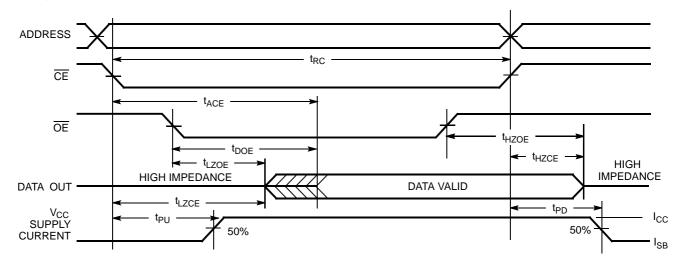


Switching Waveforms

Read Cycle No.1^[11, 12]



Read Cycle No. 2 (OE Controlled)[12, 13]

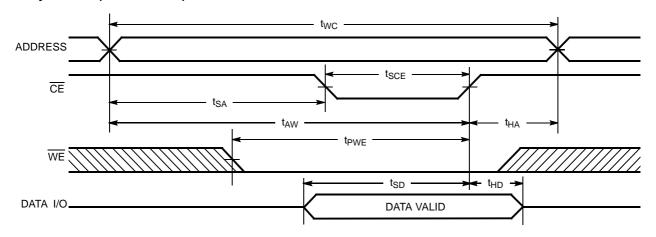


Notes:

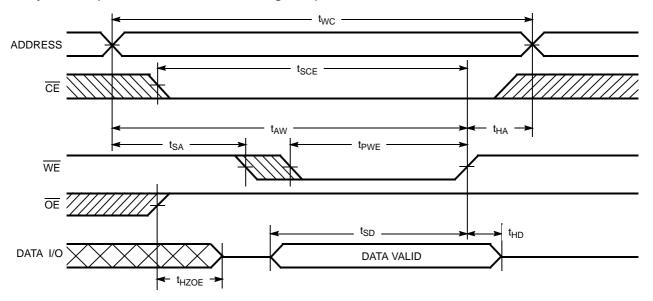
- 10. No input may exceed V_{CC} +0.5V. 11. Device is continuously selected, \overline{OE} and $\overline{CE} = V_{IL}$. 12. \overline{WE} is HIGH for read cycle.
- 13. Address valid prior to or coincident with $\overline{\sf CE}$ transition LOW.



Switching Waveforms (continued) Write Cycle No. 1 (CE Controlled)[14, 15]



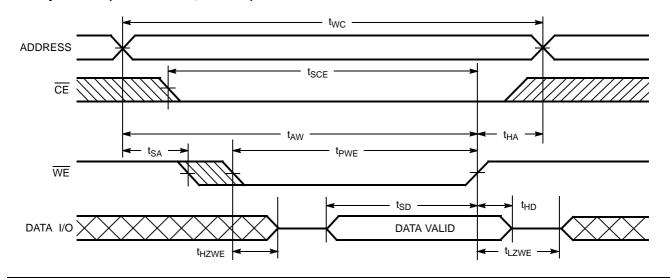
Write Cycle No. 2 (WE Controlled, OE HIGH During Write)[14, 15]



Notes: 14. If CE goes HIGH simultaneously with $\overline{\text{WE}}$ going HIGH, the output remains in a high-impedance state. 15. Data I/O is high impedance if $\overline{\text{OE}} = V_{\text{IH}}$.



Switching Waveforms (continued) Write Cycle No. 3 (WE Controlled, OE LOW)^[9, 15]



Truth Table

CE	OE	WE	Input/Output	Mode	Power
Н	Х	Х	High Z	Power-Down	Standby (I _{SB})
L	L	Н	Data Out	Read	Active (I _{CC})
L	Х	L	Data In	Write	Active (I _{CC})
L	Н	Н	High Z	Selected, Outputs Disabled	Active (I _{CC})

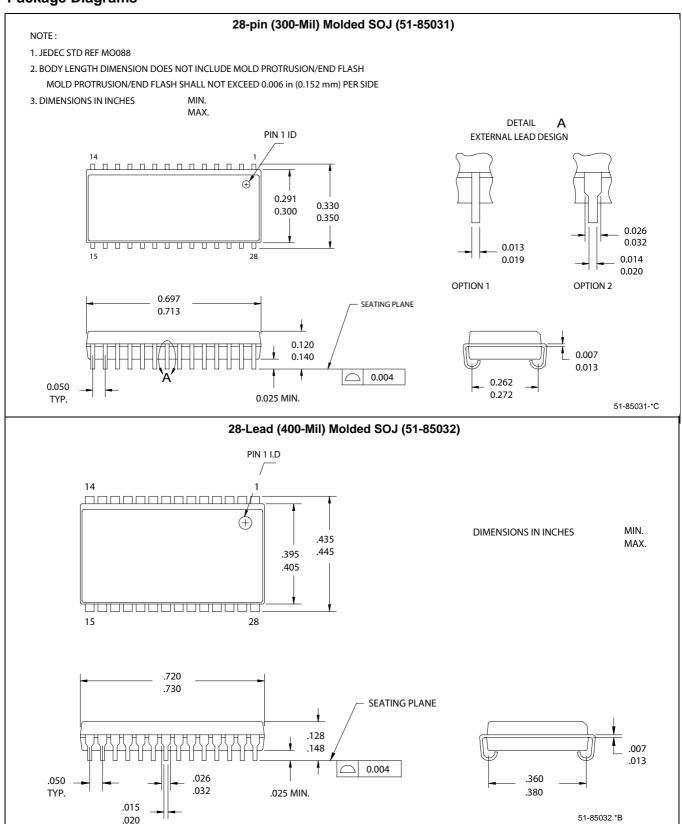
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C106BN-15VC	51-85032	28-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1006BN-15VC	51-85031	28-Lead (300-Mil) Molded SOJ	1
20	CY7C106BN-20VC	51-85032	28-Lead (400-Mil) Molded SOJ	Commercial

Please contact local sales representative regarding availability of these parts.



Package Diagrams



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Document History Page

	Document Title: CY7C106BN/CY7C1006BN 256K x 4 Static RAM Document Number: 001-06429						
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change			
**	423847	See ECN	NXR	New Data sheet			